

# Local Valence Electronic State of HfSi<sub>2</sub> Surface Component on Low-Indexed Si(110) Substrate

Takuhiro TAKIUCHI<sup>1,\*</sup>, Daisuke KOYAMA<sup>1</sup>, Kazuhiko MASE<sup>2,3</sup>, and Shin-ichi NAGAOKA<sup>1</sup>

<sup>1</sup> Ehime University, 2-5 Bunkyo-cho, Matsuyama, Ehime 790-8577, Japan

<sup>2</sup> Photon Factory, 1-1 Oho, Tsukuba, Ibaraki 305-0801, Japan

<sup>3</sup> SOKENDAI, 1-1 Oho, Tsukuba, Ibaraki 305-0801, Japan

## 1 Introduction

Downsizing of metal-oxide-semiconductor field effect transistor (MOS-FET) in development of silicon semiconductor industry has achieved large integration, high speed processing, light weighting, and on. On the other hand, it has led to a critical issue that a leakage current through ultrathin silicon dioxide (SiO<sub>2</sub>) film (< 20 Å) as gate insulating film happens due to direct tunneling effect. Therefore, a hafnium dioxide (HfO<sub>2</sub>,  $k \approx 25$ ) as high dielectric constant material is attracting high attentions as an alternative for SiO<sub>2</sub> in order to prevent the leakage current. The application of HfO<sub>2</sub> into MOS-FET will offer that the physical thickness of the gate oxide film could be increased for reduction of serious leakage current. Nevertheless, a matter that arises here is that hafnium silicide (HfSi<sub>2</sub>) component which inevitably generates around interface of HfO<sub>2</sub>/Si structure will cause unstable behaviors of the MOS-FET because they have narrower bandgap in comparison with HfO<sub>2</sub>. Therefore, it is important to reveal the local valence electric states of HfSi<sub>2</sub>/Si structure depending on the size, thickness, chemical environment, and so on. [1]

In addition, the MOS-FET structure renewed from 2 dimensions (Ds) to 3Ds will be another approach so as to keep up with the development of MOS-FET performance. Therefore, low-indexed Si(110) substrate which shows unique single domain (SD) structure with atomic scaled 3Ds concave-convex is also an promising candidate for next generation.[2, 3]

In this report, we prepared HfSi<sub>2</sub> islands on a clean Si(110)-16×2 surface [*i*-HfSi<sub>2</sub>/Si(110)] and investigated site specific local valence electronic state of *i*-HfSi<sub>2</sub> surface component with Si *L*<sub>23</sub>*VV* Auger-electron – Si 2*p* photoelectron coincidence spectroscopy (Si-*L*<sub>23</sub>*VV*-Si-2*p* APECS). The core-valence-valence (*CVV*) Auger electron spectrum measured with Si-*L*<sub>23</sub>*VV*-Si-2*p* APECS can provide the two holes valence electronic structure in the vicinity of a specific *i*-HfSi<sub>2</sub> component.

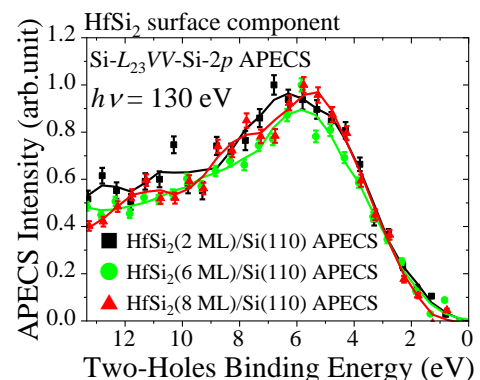
## 2 Experiment

A clean Si(110)-16×2 with SD surface was prepared by direct current heating over 1523 K in UHV less than  $2.0 \times 10^{-7}$  Pa. After then, ultrathin Hf films with the different thickness of ~2, 6, and 8 ML (monolayer, 1 ML = 2.4 Å [4]) were deposited on the clean Si(110)-16×2 surface by means of electron bombardment method. They were directly turned into *i*-HfSi<sub>2</sub>/Si(110) structure by annealing at 1073 K.

Si-*L*<sub>23</sub>*VV*-Si-2*p* APECS measurements were performed with a handmade electron-electron-ion coincidence analyzer at BL-11D in PF, KEK. The photon energy ( $h\nu$ ) was fixed at 130 eV for ionization of Si 2*p* core levels.

## 3 Results and Discussion

Fig. 1 shows the Si-*L*<sub>23</sub>*VV*-Si-2*p* APECS spectra which selected the only HfSi<sub>2</sub> surface component from some *i*-HfSi<sub>2</sub>/Si(110) structures. These are drawn on two-holes binding energy scale of Si *L*<sub>23</sub>*VV* Auger final states. When comparing these results, they are mostly the same spectral distributions. This indicates that the local valence electronic state at HfSi<sub>2</sub> surface component does not depend on the thickness of Hf deposition films because the HfSi<sub>2</sub> islands with random sizes are formed after annealing at 1073 K.



**Fig. 1:** Si-*L*<sub>23</sub>*VV*-Si-2*p* APECS spectra obtained from *i*-HfSi<sub>2</sub>/Si(110) which made from ultrathin Hf deposition films with the different thicknesses of ~2, 6, and 8 ML by annealing at 1073 K.

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\* kakiuchi.takuhiro.mc@ehime-u.ac.jp